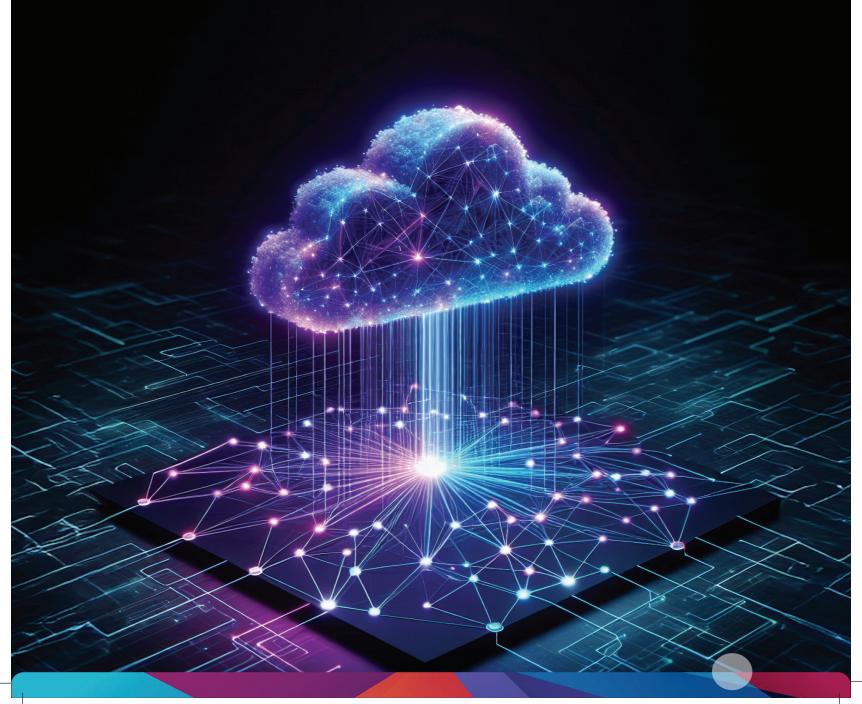
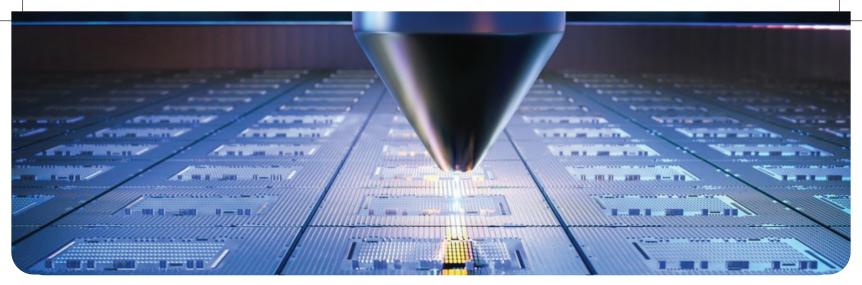
CYIENT

Delivering

INTELLIGENT ENGINEERING

From Chip to Cloud





Delivering Intelligent Engineering

Cyient brings decades of expertise in Intelligent Engineering to pioneer advancements in the semiconductor sector, fostering a digital, autonomous, and sustainable future. Our bespoke solutions for advanced semiconductor technologies, help enhance operational agility and innovation, contributing to a smarter, more sustainable electronics industry.

From Chip to Cloud

Chip Design

IC Consulting: 20+ years of experience in silicon design, development, industrialization, and supply chain management.

IC Development: Full in-house IC development, from definition and validation to physical layout.

Turnkey ASIC Solutions: End-to-end ASIC design for Analog, RF, and mixed-signal applications, suitable for all production volumes.

Post-Silicon Validation: Tailored IC manufacturing, ensuring high-quality production flows.

Chip Production

Prototype: Rapid prototyping services for accurate and dependable chip solutions.

Test & Qualification: High standards of performance, reliability, and compliance testing for semiconductor products.

Packaging: Advanced chip packaging for optimal size, power, and thermal performance.

Supply Chain Management: Efficient semiconductor production strategies to boost market readiness.

Connected Products & System Engineering

01 System Engineering



Integrated solutions to optimize performance, reliability, and lifecycle costs.

02 Product Development



Cost-effective solutions enhancing product lifecycle success.

03 Test Automation



Efficient automation tools (CyFast) to enhance testing processes and productivity.

Industry 4.0 & Digital Transformation

PLM: Proactive Product Lifecycle Management for semiconductor processes.

Manufacturing Automation: Comprehensive solutions for improving productivity, safety, and sustainability.

Cloud & Data Analytics: Scalable microservices and data platforms to facilitate digital transformation and improve engineering outcomes.

Did You Know?

Cyient designed India's first 5G Narrow-Band IoT Chip. System on chip tailored for IoT, featuring an NBIoT front-end, uSIM interface, integrated PMU, and GPS for precise location tracking. Its versatile digital core boasts processors and diverse interfaces, ideal for various smart-tech solutions including home automation, fleet management, and wearables.



To know more, please check out https://www.cyient.com/semiconductor.

About Cyient

Cyient (Estd: 1991, NSE: CYIENT) partners with over 300 customers, including 40% of the top 100 global innovators of 2023, to deliver intelligent engineering and technology solutions for creating a digital, autonomous, and sustainable future. As a company, Cyient is committed to designing a culturally inclusive, socially responsible, and environmentally sustainable Tomorrow Together with our stakeholders.

For more information, please visit www.cyient.com



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